

**Abstract of the Disclosure**

According to the present invention, individual two-dimensional barcodes 30, 91 and 173 are provided for individual chips 31 arrayed on a wafer 50, individual lead frames 93 to each of which chips 92 are bonded and individual packaged products 171 constituted of resin sealed semiconductor chips based upon chip ID information to enable information management to be implemented separately for individual chips 31, individual frames 93 and individual chip products 171. Thus, a higher degree of efficiency and a higher degree of accuracy in the information management for semiconductor devices are achieved in all processes of semiconductor production including the individual manufacturing processes, the physical distribution process, the shipping process and the claim handling process.